

# SETNA FC150

- SETNA (formerly Suss Microtech) FC150 is located in a Class-100 cleanroom.
- Eutectic die bonding, compression bonding and adhesive bonding are all achievable on this system. Wafer bonding of up to 2 inch wafers is possible with tooling.
- Precision alignment prior to bonding with automated programmable recipes for all bonding cycles.

